5-146282-4 ACTIVE

AMPMODU | AMPMODU Headers

TE Internal #: 5-146282-4

PCB Mount Header, Vertical, Board-to-Board, 4 Position, 2.54 mm [.

1 in] Centerline, Breakaway, Tin, Through Hole - Solder, Signal,

AMPMODU Headers

View on TE.com >

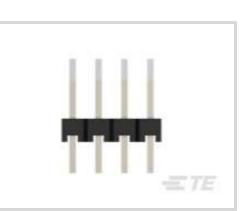


Connectors > PCB Connectors > PCB Headers & Receptacles











PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical
Connector System: Board-to-Board

Number of Positions: 4
Number of Rows: 1

Features

Product Type Features

| PCB Connector Assembly Type | PCB Mount Header |
|-----------------------------------|-----------------------|
| Connector System | Board-to-Board |
| Header Type | Breakaway |
| Sealable | No |
| Connector & Contact Terminates To | Printed Circuit Board |

Configuration Features

| Connector Contact Load Condition | Fully Loaded |
|----------------------------------|--------------|
| PCB Mount Orientation | Vertical |
| Number of Positions | 4 |
| Number of Rows | 1 |
| Board-to-Board Configuration | Parallel |

Body Features

| Primary Product Color Bla | ack |
|---------------------------|-----|
|---------------------------|-----|



| Matting Square Post Dimension Contact Shape & Form Square Contact Underplating Material PCB Contact Termination Area Plating Material Contact Base Material Contact Base Material Contact Mating Asea Plating Material Thickness Contact Type Conta | | |
|--|--|-------------------------------|
| Contact Shape & Form Contact Underplating Material PCB Contact Termination Area Plating Material Tin Contact Base Material Copper Alloy Contact Mating Area Plating Material Tin Contact Uype Pin Contact Current Rating (Max) 3.A Termination Features Square Termination Post & Tail Dimension Termination Post & Tail Dimension Termination Post & Tail Dimension Termination Method to Printed Circuit Board Through Hole - Solder Mechanical Attachment Mating Alignment Without PCB Mount Retention Without PCB Mount Retention Without Connector Mounting Lype Board Mount Housing Features Centerline (Pitch) 2.54 mm(.1 in) Housing Material LCP (Liquid Crystal Polymer), LCP GF (Liquid Crystal Polymer) Dimensions PCB Thickness (Recommended) Usage Conditions Llousing Temperature Rating Usage Operating Temperature Range Operating Temperature Range Operating Application Circuit Application Signal Industry Standards | Mating Square Post Dimension | .64 mm[.025 in] |
| Contact Underplating Material PCB Contact Termination Area Plating Material Tin Contact Base Material Contact Mating Area Plating Material Contact Mating Area Plating Material Contact Mating Area Plating Material Thickness 2.54 – 5.08 µm/100 – 200 µm/1 Contact Type Pin Contact Type Contact Gurrent Rating (Max) 3.A Termination Features Sequare Termination Post & Tail Length 2.29 mm/09 in/1 Termination Post & Tail Length 2.29 mm/09 in/1 Termination Method to Printed Circuit Board Through Hole - Solder Mechanical Attachment Mating Alignment Without PCB Mount Retention PCB Mount Alignment Without Connector Mounting Type Board Mount Housing Features Centerline (Pitch) 2.54 mm/1 in/1 Housing Material LCP (Liquid Crystal Polymer), LCP GF (Liquid Crystal Polymer) Dimensions PCB Thickness (Recommended) 1.6 mm/063 in/1 Usage Conditions Housing Temperature Rating Operating Temperature Range -65 – 105 "CL-85 – 221 "FT Operation/Application Circuit Application Signal Industry Standards | | 100 – 200 μin |
| PCB Contact Termination Area Plating Material Contact Base Material Contact Mating Area Plating Material Contact Mating Area Plating Material Contact Mating Area Plating Material Thickness 2.54 – 5.08 µm[100 – 200 µin] Contact Type Pin Contact Gurrent Rating (Max) 3.A Termination Features Square Termination Post & Tail Dimension Jermination Post & Tail Dimension Jermination Post & Tail Dimension Jermination Method to Printed Circuit Board Through Hole – Solder Mechanical Attachment Mating Alignment Without PCB Mount Retention PCB Mount Alignment Without Connector Mounting Type Board Mount Housing Features Centerline (Pitch) Jermination Under PCB Thickness (Recommended) Jerminature Rating Housing Temperature Rating Operating Temperature Rating Operating Temperature Range Operation/Application Gircuit Application Signal Industry Standards | Contact Shape & Form | Square |
| Contact Base Material Copper Alloy Contact Mating Area Plating Material Tin Contact Mating Area Plating Material Thickness 2.54 – 5.08 µm[100 – 200 µin] Contact Type Pin Contact Current Rating (Max) 3 A Termination Features Square Termination Post & Tail Dimension .64 mm[.025 in] Termination Features Square Termination Method to Printed Circuit Board Through Hole - Solder Mechanical Attachment Mating Alignment Without PCB Mount Retention Without PCB Mount Alignment Without Connector Mounting Type Board Mount Housing Features Centerline (Pitch) 2.54 mm[.1 in] Housing Material LCP (Liquid Crystal Polymer), LCP GF (Liquid Crystal Polymer) Dimensions PCB Thickness (Recommended) 1.6 mm[.063 in] Usage Conditions Housing Temperature Rating High Operation/Application Circuit Application Signal Industry Standards | Contact Underplating Material | Nickel |
| Contact Mating Area Plating Material Contact Mating Area Plating Material Thickness 2.54 – 5.08 µm[100 – 200 µin] Contact Type Pin Contact Current Rating (Max) 3.A Termination Features Square Termination Post & Tail Dimension 4.64 mm[.025 in] Termination Post & Tail Length 2.29 mm[.09 in] Termination Method to Printed Circuit Board Through Hole - Solder Mechanical Attachment Mating Alignment PCB Mount Retention Without PCB Mount Alignment Without Connector Mounting Type Board Mount Housing Features Centerline (Fitch) 2.54 mm[.1 in] Housing Material LCP (Liquid Crystal Polymer), LCP-GF (Liquid Crystal Polymer) Dimensions PCB Thickness (Recommended) 1.6 mm[.063 in] Usage Conditions Housing Temperature Rating Operating Temperature Range -65 – 105 °C[.85 – 221 °F] Operation/Application Circuit Application Signal | PCB Contact Termination Area Plating Material | Tin |
| Contact Mating Area Plating Material Thickness 2.54 – 5.08 µm[100 – 200 µin] Contact Type Pin Contact Current Rating (Max) 3.A Termination Features Square Termination Post & Tail Dimension .64 mm[.025 in] Termination Method to Printed Circuit Board Through Hole - Solder Mechanical Attachment Mating Alignment Without PCB Mount Retention Without PCB Mount Alignment Without Connector Mounting Type Board Mount Housing Features Centerline (Pitch) 2.54 mm[.1 in] Housing Material LCP (Liquid Crystal Polymer), LCP-GF (Liquid Crystal Polymer) Dimensions PCB Thickness (Recommended) 1.6 mm[.063 in] Usage Conditions Housing Temperature Rating High Operating Temperature Rating65 – 105 °C[-85 – 221 °F] Operation/Application Circuit Application Industry Standards | Contact Base Material | Copper Alloy |
| Contact Type Pin 3 A Secondaria Contact Current Rating (Max) 3 A Secondaria Current Rating (Max) 3 A S | Contact Mating Area Plating Material | Tin |
| Termination Features Square Termination Post & Tail Dimension .64 mml,025 in] Termination Post & Tail Length .2.29 mml,09 in] Termination Method to Printed Circuit Board .Through Hole - Solder Mechanical Attachment Mating Alignment .Without PCB Mount Retention .Without PCB Mount Alignment .Without Connector Mounting Type .Board Mount Housing Features Centerline (Pitch) .2.54 mml,1 in] Housing Material .LCP (Liquid Crystal Polymer), LCP GF (Liquid Crystal Polymer) Dimensions PCB Thickness (Recommended) .1.6 mml,063 in] Usage Conditions Housing Temperature Rating .High Operation/Application Circuit Application .Signal Industry Standards | Contact Mating Area Plating Material Thickness | 2.54 – 5.08 μm[100 – 200 μin] |
| Termination Features Square Termination Post & Tail Dimension | Contact Type | Pin |
| Square Termination Post & Tail Length 2.29 mm[.09 in] Termination Method to Printed Circuit Board Through Hole - Solder Mechanical Attachment Mating Alignment Without PCB Mount Retention Without PCB Mount Alignment Without Connector Mounting Type Board Mount Housing Features Centerline (Pitch) 2.54 mm[.1 in] Housing Material LCP (I iquid Crystal Polymer), LCP GF (I iquid Crystal Polymer) Dimensions PCB Thickness (Recommended) 1.6 mm[.063 in] Usage Conditions Housing Temperature Rating High Operation/Application Circuit Application Signal Industry Standards | Contact Current Rating (Max) | 3 A |
| Termination Post & Tail Length Termination Method to Printed Circuit Board Mechanical Attachment Mating Alignment PCB Mount Retention Without PCB Mount Alignment Without Connector Mounting Type Board Mount Housing Features Centerline (Pitch) LCP (Liquid Crystal Polymer), LCP GF (Liquid Crystal Polymer) Dimensions PCB Thickness (Recommended) 1.6 mm[.063 in] Usage Conditions Housing Temperature Rating Operating Temperature Range Operation/Application Circuit Application Industry Standards | Termination Features | |
| Termination Method to Printed Circuit Board Mechanical Attachment Mating Alignment PCB Mount Retention Without PCB Mount Alignment Without Connector Mounting Type Board Mount Housing Features Centerline (Pitch) LCP (Liquid Crystal Polymer), LCP-GF (Liquid Crystal Polymer) Dimensions PCB Thickness (Recommended) 1.6 mm[.063 in] Usage Conditions Housing Temperature Rating Operating Temperature Range Operation/Application Circuit Application Signal Industry Standards | Square Termination Post & Tail Dimension | .64 mm[.025 in] |
| Mechanical Attachment Mating Alignment PCB Mount Retention Without PCB Mount Alignment Without Connector Mounting Type Board Mount Housing Features Centerline (Pitch) LCP (Liquid Crystal Polymer), LCP-GF (Liquid Crystal Polymer) Dimensions PCB Thickness (Recommended) 1.6 mm[.063 in] Usage Conditions Housing Temperature Rating High Operating Temperature Range Operation/Application Circuit Application Industry Standards | Termination Post & Tail Length | 2.29 mm[.09 in] |
| Mating Alignment PCB Mount Retention Without Without Connector Mounting Type Board Mount Housing Features Centerline (Pitch) LCP (Liquid Crystal Polymer), LCP-GF (Liquid Crystal Polymer) Dimensions PCB Thickness (Recommended) 1.6 mm[.063 in] Usage Conditions Housing Temperature Rating Operating Temperature Range Circuit Application Circuit Application Industry Standards | Termination Method to Printed Circuit Board | Through Hole - Solder |
| PCB Mount Retention Without PCB Mount Alignment Without Connector Mounting Type Board Mount Housing Features Centerline (Pitch) 2.54 mm[.1 in] Housing Material LCP (Liquid Crystal Polymer), LCP-GF (Liquid Crystal Polymer) Dimensions PCB Thickness (Recommended) 1.6 mm[.063 in] Usage Conditions Housing Temperature Rating High Operating Temperature Range -65 – 105 °C[-85 – 221 °F] Operation/Application Circuit Application Signal Industry Standards | Mechanical Attachment | |
| PCB Mount Alignment Connector Mounting Type Board Mount Housing Features Centerline (Pitch) LCP (Liquid Crystal Polymer), LCP-GF (Liquid Crystal Polymer) Dimensions PCB Thickness (Recommended) 1.6 mm[.063 in] Usage Conditions Housing Temperature Rating Operating Temperature Range Operation/Application Circuit Application Industry Standards | Mating Alignment | Without |
| Connector Mounting Type Housing Features Centerline (Pitch) Housing Material LCP (Liquid Crystal Polymer), LCP-GF (Liquid Crystal Polymer) Dimensions PCB Thickness (Recommended) 1.6 mm[.063 in] Usage Conditions Housing Temperature Rating High Operating Temperature Range -65 – 105 °C[-85 – 221 °F] Operation/Application Circuit Application Industry Standards | PCB Mount Retention | Without |
| Housing Features Centerline (Pitch) LCP (Liquid Crystal Polymer), LCP-GF (Liquid Crystal Polymer) Dimensions PCB Thickness (Recommended) 1.6 mm[.063 in] Usage Conditions Housing Temperature Rating Operating Temperature Range -65 – 105 °C[-85 – 221 °F] Operation/Application Circuit Application Signal Industry Standards | PCB Mount Alignment | Without |
| Centerline (Pitch) Housing Material LCP (Liquid Crystal Polymer), LCP-GF (Liquid Crystal Polymer) Dimensions PCB Thickness (Recommended) 1.6 mm[.063 in] Usage Conditions Housing Temperature Rating Operating Temperature Range -65 – 105 °C[-85 – 221 °F] Operation/Application Circuit Application Signal Industry Standards | Connector Mounting Type | Board Mount |
| Housing Material LCP (Liquid Crystal Polymer), LCP-GF (Liquid Crystal Polymer) Dimensions PCB Thickness (Recommended) 1.6 mm[.063 in] Usage Conditions Housing Temperature Rating Operating Temperature Range -65 – 105 °C[-85 – 221 °F] Operation/Application Circuit Application Signal Industry Standards | Housing Features | |
| (Liquid Crystal Polymer) Dimensions PCB Thickness (Recommended) 1.6 mm[.063 in] Usage Conditions Housing Temperature Rating Operating Temperature Range -65 – 105 °C[-85 – 221 °F] Operation/Application Circuit Application Signal Industry Standards | Centerline (Pitch) | 2.54 mm[.1 in] |
| PCB Thickness (Recommended) Usage Conditions Housing Temperature Rating Operating Temperature Range -65 – 105 °C[-85 – 221 °F] Operation/Application Circuit Application Signal Industry Standards | Housing Material | |
| Usage Conditions Housing Temperature Rating Operating Temperature Range -65 – 105 °C[-85 – 221 °F] Operation/Application Circuit Application Signal Industry Standards | Dimensions | |
| Housing Temperature Rating Operating Temperature Range -65 – 105 °C[-85 – 221 °F] Operation/Application Circuit Application Signal Industry Standards | PCB Thickness (Recommended) | 1.6 mm[.063 in] |
| Operating Temperature Range65 – 105 °C[-85 – 221 °F] Operation/Application Circuit Application Signal Industry Standards | Usage Conditions | |
| Operation/Application Circuit Application Signal Industry Standards | Housing Temperature Rating | High |
| Circuit Application Signal Industry Standards | Operating Temperature Range | -65 – 105 °C[-85 – 221 °F] |
| Industry Standards | Operation/Application | |
| | Circuit Application | Signal |
| Approved Standards CSA LR7189, UL E28476 | Industry Standards | |
| | Approved Standards | CSA LR7189, UL E28476 |



UL Flammability Rating UL 94V-0

Packaging Features

| Packaging Quantity | 500 |
|--------------------|--------|
| Packaging Type | Carton |

Product Compliance

For compliance documentation, visit the product page on TE.com>

| EU RoHS Directive 2011/65/EU | Compliant |
|---|---|
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC |
| Halogen Content | Low Bromine/Chlorine - Br and Cl < 900 ppm per homogenous material. Also BFR /CFR/PVC Free |
| Solder Process Capability | Pin-in-Paste capable to 260°C |

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts









Also in the Series | AMPMODU Headers



PCB Connector Mounting(1)



PCB Connector Shrouds(1)



PCB Headers & Receptacles(4875)



PCB Latches, Locks & Retainers(1)



Wire-to-Board Connector Assemblies & Housings(5)

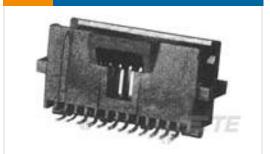


Wire-to-Board Connector Contacts(65)

Customers Also Bought



TE Part #5750678-1
09 RCPT SP/FMS (RET SL)



TE Part #5-104549-7 50 SYS50 S/M HDR DRST SHRDSN



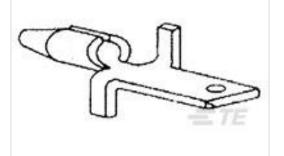
TE Part #1761606-6
IDC LOW PRO HDR 16P VERT LG LAT
BLK



TE Part #2-1761606-5
IDC LOW PRO HDR 14P VERT LG LA



TE Part #5-103735-2 03 MTE HDR SRST LATCH .100CL



TE Part #61968-1 110 FASTON TAB TPBR



TE Part #1649329-4 RTE24012

TE Part #1761651-2 IDC LOW PRO HDR 29/40P VERT SH





Documents

Product Drawings

04 MODII HDR SRST B/A .100CL

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_5-146282-4_F.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_5-146282-4_F.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_5-146282-4_F.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Environmental Compliance

MD_5-146282-4_012320122347

English

MD_5-146282-4_012320122347

English